**QS16G (E) Package Outline Drawing**

![QS16G (E) Package Outline Drawing](image)

**Package Information**

<table>
<thead>
<tr>
<th></th>
<th></th>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>QS16G</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [^1]</td>
<td>HMCNNN XXXX</td>
</tr>
<tr>
<td>QS16GE</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [^2]</td>
<td>HMCNNN XXXX</td>
</tr>
</tbody>
</table>

[^1]: Max peak reflow temperature of 235 °C
[^2]: Max peak reflow temperature of 260 °C
[^3]: 4-Digit lot number XXXX
[^4]: 3-Digit part number NNN

**NOTES:**
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
Suggested QS16G (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.